



ACTRON TECHNOLOGY CORP.

Features

- Best thermal conductivity and behavior
- High speed switching
- High robustness of dv/dt
- Low capacitances and low gate charge
- Low gate resistance for high-frequency switching
- Easy to parallel

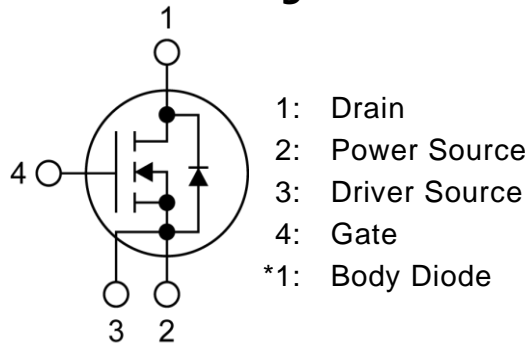
Outline (TO247-4L)



Applications

- Switching mode power supply
- PV inverter
- Uninterruptible Power Supply
- Motor Drives
- DC/DC converters
- EV charging

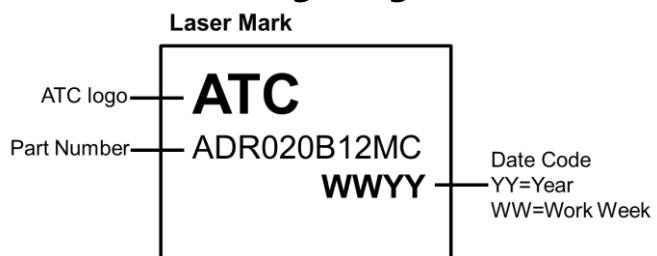
Circuit Diagram



Mechanical Characteristics

- TO247-4L package
- Halogen Free
- Pb free lead plating ; RoHS compliant
- Packaging: Tube

Marking Diagram



**Absolute Maximum Rating ($T_a = 25^\circ\text{C}$)**

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source voltage	1200	V
V_{GSS}	Gate-Source voltage (DC)	-4 to 20	V
I_D	Continuous Drain Current	95	A
I_{DP}	Pulse Drain Current	190	A
T_j	Junction temperature	175	$^\circ\text{C}$
T_{STG}	Storage temperature	-55/+175	$^\circ\text{C}$
P_D	Power dissipation	465	W

Thermal characteristics

Parameter	Symbol	Condition	Typ.	Unit
Thermal resistance	θ_{jc}	Junction - Case	0.2	$^\circ\text{C} / \text{W}$

Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Condition
$V_{(BR)DSS}$	Drain-Source breakdown voltage	1200	-	-	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
I_{DSS}	Zero gate voltage drain current	-	6.0 12	60 -	μA	$V_{DS} = 1200\text{V}, V_{GS} = 0\text{V}, T_j = 25^\circ\text{C}$ $V_{DS} = 1200\text{V}, V_{GS} = 0\text{V}, T_j = 150^\circ\text{C}$
$R_{DS(on)}$	Drain-Source on-state resistance	-	20 40	26 -	$\text{m}\Omega$	$V_{GS} = 18\text{V}, I_D = 47.5\text{A}, T_j = 25^\circ\text{C}$ $V_{GS} = 18\text{V}, I_D = 47.5\text{A}, T_j = 125^\circ\text{C}$
$V_{GS(th)}$	Gate threshold voltage	2.0	-	3.0	V	$V_{DS} = 10\text{V}, I_D = 10\text{mA}$
I_{GSS+}	Gate-Source leakage current	-	-	100	nA	$V_{GD} = 20\text{V}, V_{DS} = 0\text{V}$
I_{GSS-}	Gate-Source leakage current	-	-	-100	nA	$V_{GD} = -4\text{V}, V_{DS} = 0\text{V}$
R_G	Gate resistance	-	2.0	-	Ω	$f = 1\text{MHz}, \text{open drain}$

**Electrical Characteristics (Ta = 25 °C)**

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Condition
C _{iss}	Input capacitance	-	5600	-	pF	V _{GS} = 0V V _{DS} = 800V f = 1MHz
C _{oss}	Output capacitance	-	210	-	pF	
C _{rss}	Reverse capacitance	-	30	-	pF	
Q _g	Total gate charge	-	280	-	nC	V _{DS} = 800V I _D = 47.5A V _{GS} = 18V
Q _{gs}	Gate to source charge	-	45	-	nC	
Q _{gd}	Gate to drain charge	-	110	-	nC	
t _{d(on)}	Turn - on delay time	-	31	-	ns	V _{DS} =800V V _{GS} =0V/+18V R _{GS} =2Ω
t _r	Rise time	-	34	-	ns	
t _{d(off)}	Turn - off delay time	-	70	-	ns	
t _f	Fall time	-	14	-	ns	

Body diode Electrical Characteristics (Ta = 25 °C)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Condition
I _S	Body diode continuous, forward current	-	-	95	A	
V _{SD}	Diode forward voltage	-	4	-	V	V _{GS} = 0V, I _S = 47.5A
t _{rr}	Reverse recovery time		36		ns	I _{SD} =47.5A V _R =800V di/dt=1000A/us
I _{rrm}	Peak reverse recovery current		20		A	



Typical Output Characteristics (I)

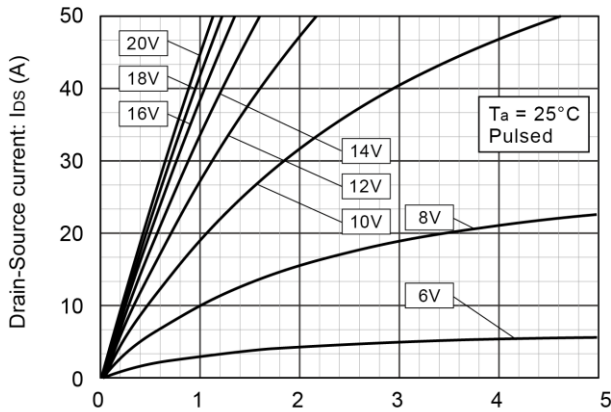


Figure1. Drain - Source Voltage: Vds (V)

Typical Output Characteristics (II)

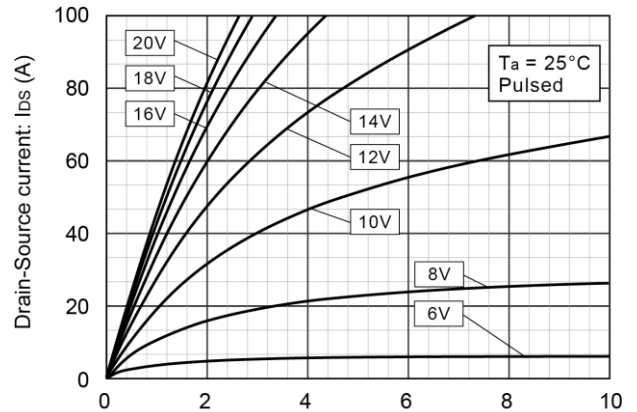


Figure2. Drain - Source Voltage: Vds (V)

Typical Output Characteristics (III) Ta =150°C

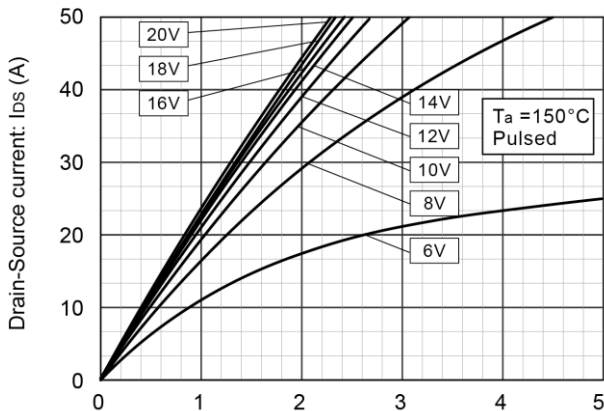


Figure3. Drain - Source Voltage: Vds (V)

Typical Output Characteristics (IV) Ta =150°C

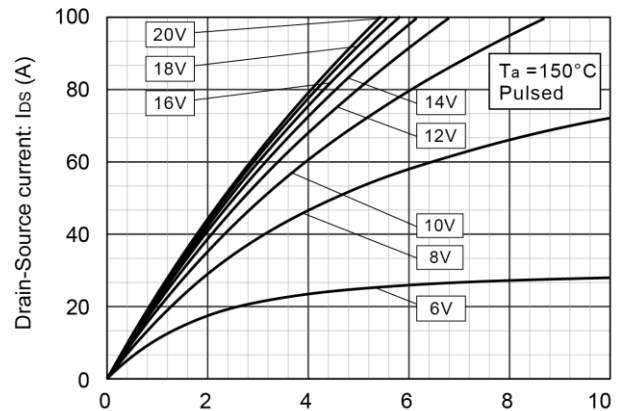


Figure4. Drain - Source Voltage: Vds (V)



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Typical Transfer Characteristics (I)

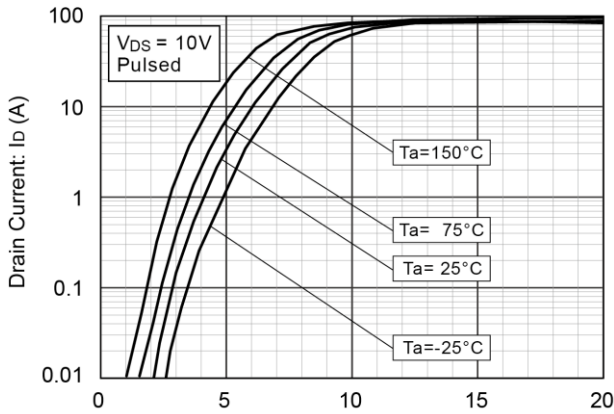


Figure5. Gate - Source Voltage: Vgs (V)

Typical Transfer Characteristics (II)

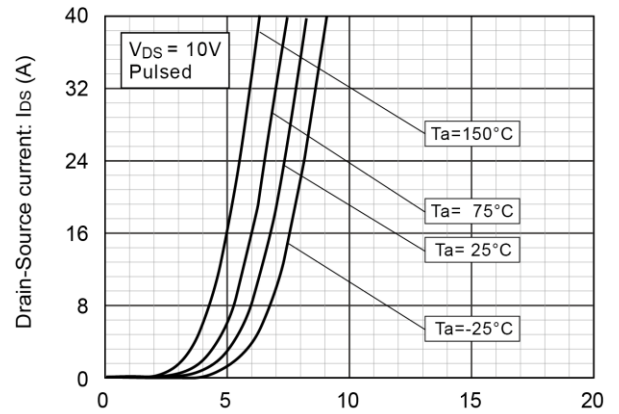


Figure6. Gate - Source Voltage: Vgs (V)

Drain - Source Voltage vs. Source - Drain current

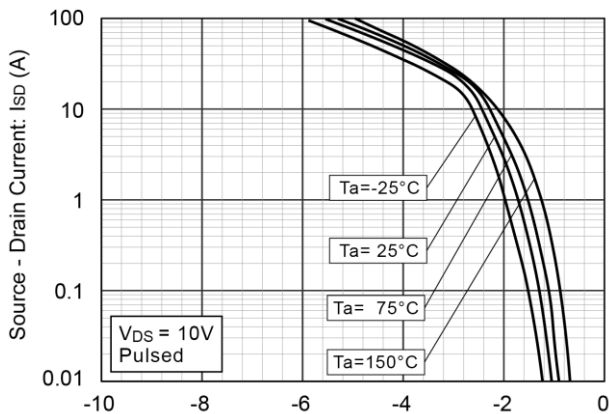


Figure7. Drain - Source Voltage: Vds (V)

3rd Quadrant Characteristic Ta = 25°C

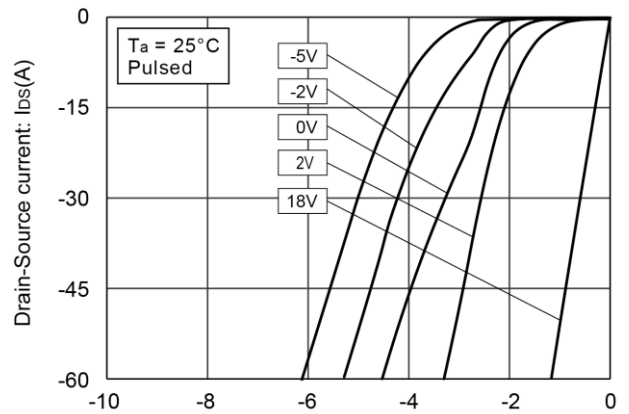


Figure8. Drain-Source Voltage: Vds (V)

Gate Threshold Voltage vs. Junction Temperature

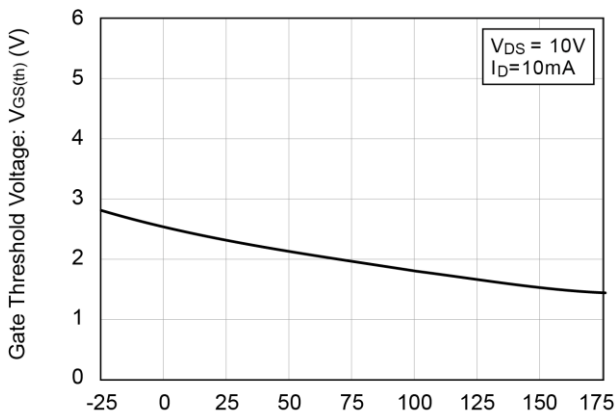


Figure9. Junction Temperature: Tj (°C)

Static Drain - Source On - State Resistance vs. Gate - Source Voltage

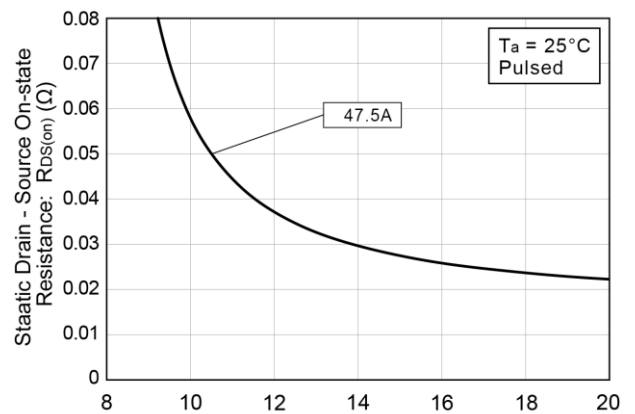


Figure10. Gate - Source Voltage: Vgs (V)



Static Drain - Source On - State Resistance vs. Junction Temperature

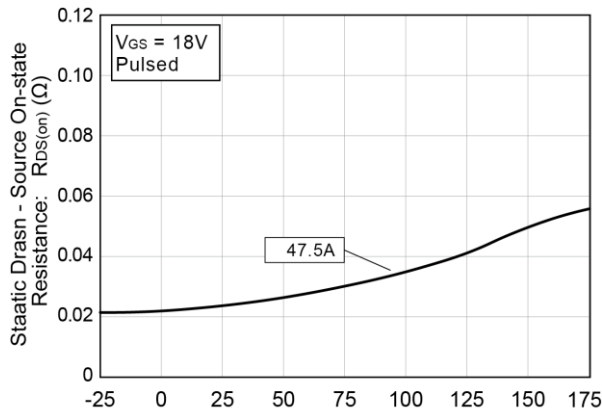


Figure11. Junction Temperature: T_j (°C)

Typical Capacitance vs. Drain - Source Voltage

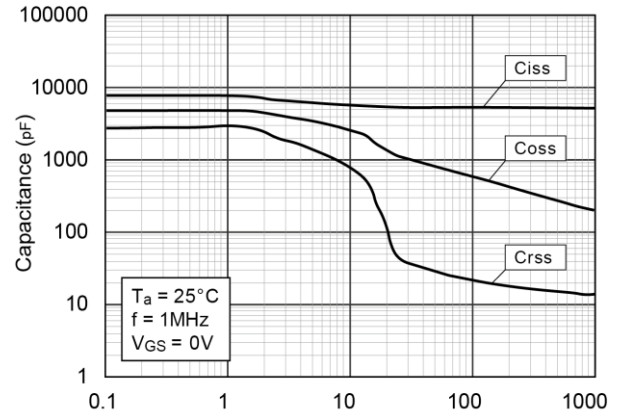


Figure12. Drain - Source Voltage: V_{ds} (V)

Typical Gate Charge

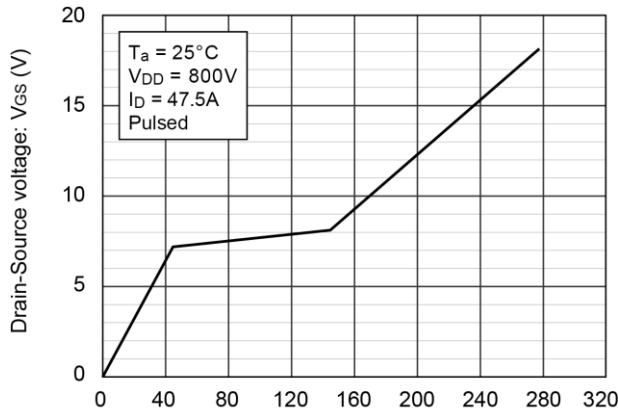


Figure13. Gate charge : Q_g (nC)

Maximum Safe Operating Area (SOA)

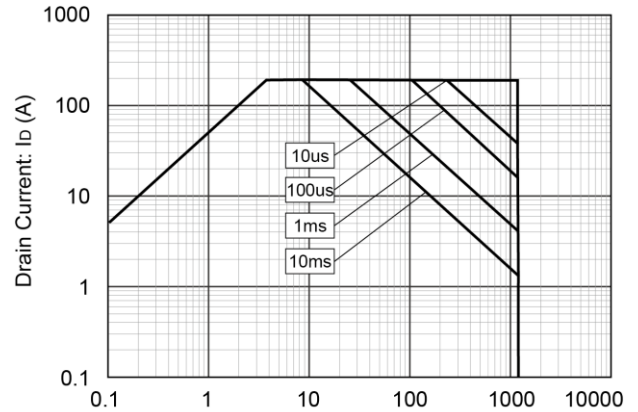


Figure16. Drain-Source Voltage: V_{ds} (V)

Reverse Bias Safe Operating Area (RBSOA)

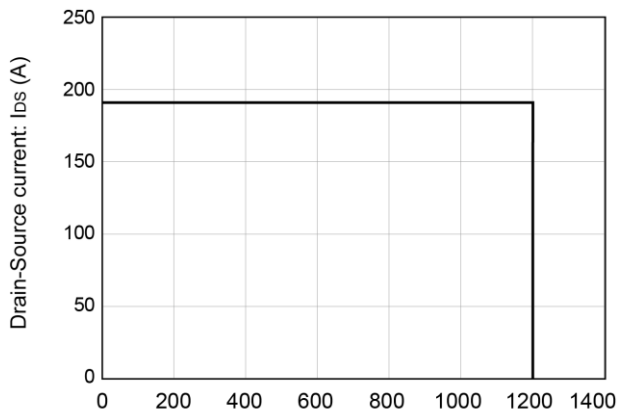


Figure17. Drain - Source Voltage: V_{ds} (V)

Typical Transient Thermal Resistance Vs. Pulse Width

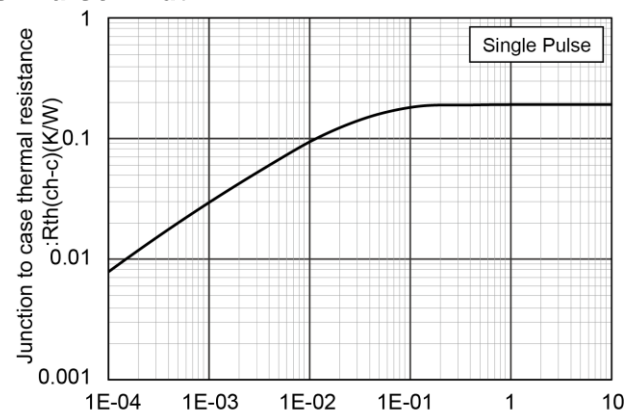
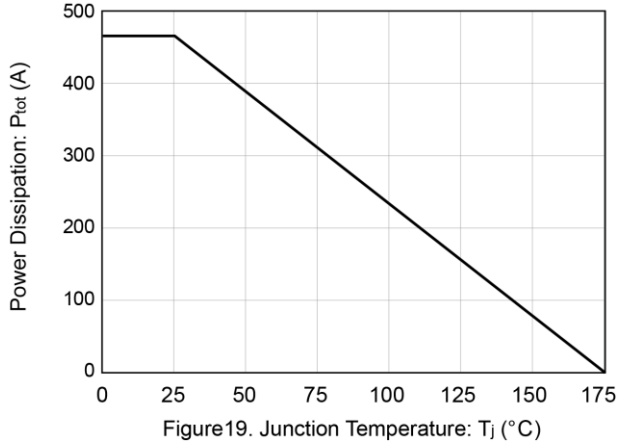


Figure18. Pulse Width: t_w (S)

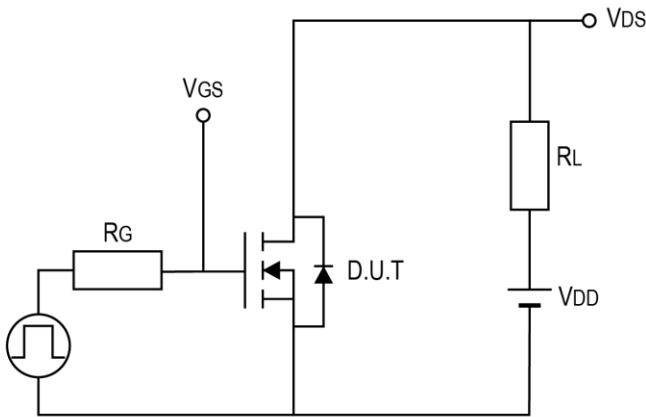


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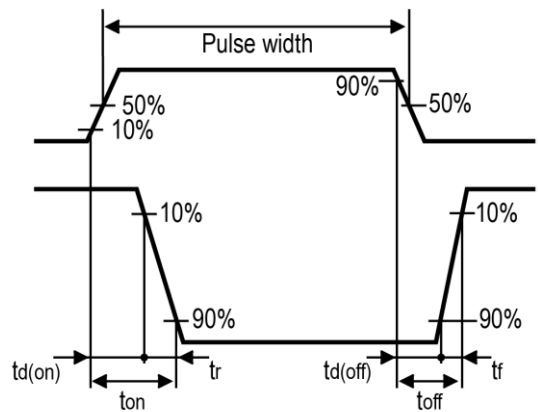
Power dissipation vs. Junction Temperature



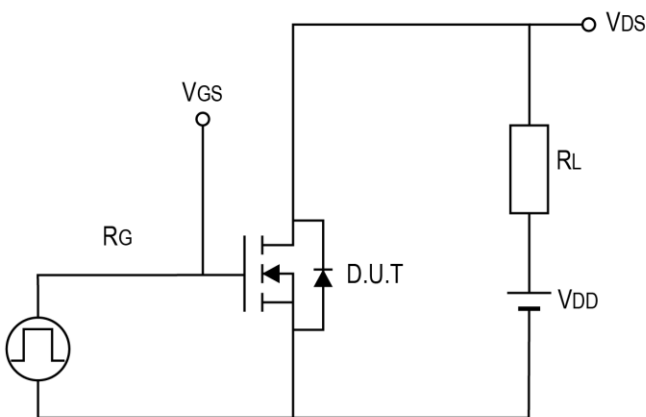
Switching Time Measurement Circuit



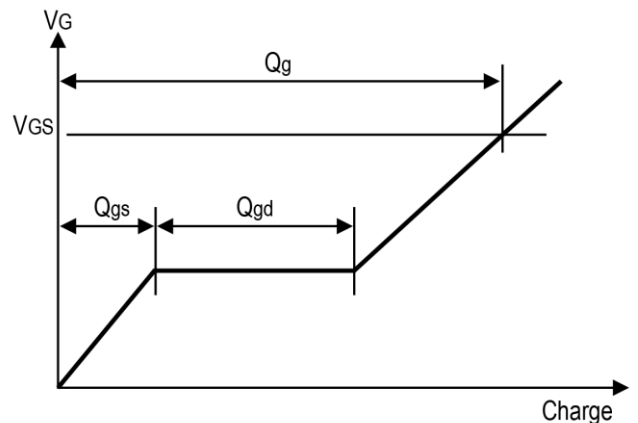
Switching Waveform



Gate Charge Measurement Circuit



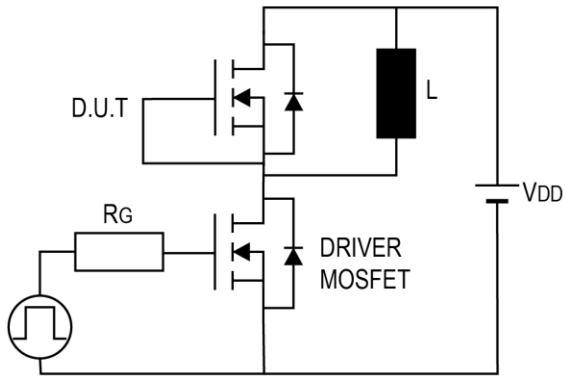
Gate Charge Waveform



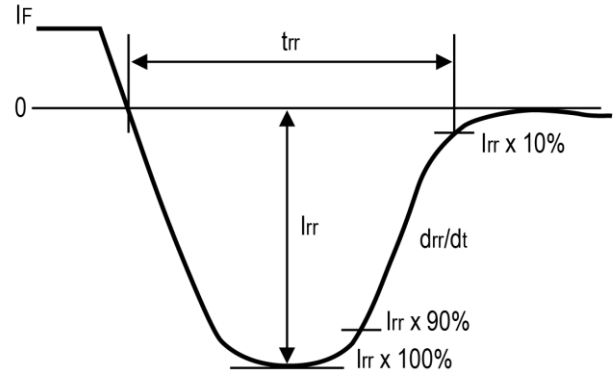


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Reverse Recovery Time Measurement Circuit



Reverse Recovery Time Waveform

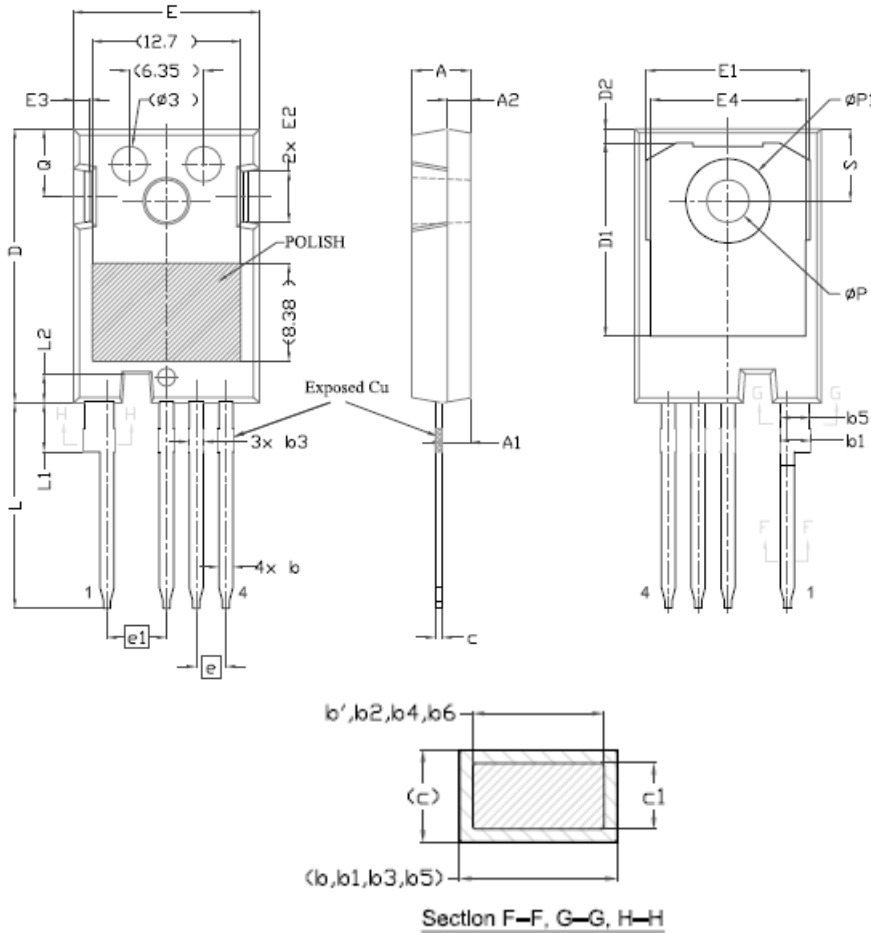




Package Outline

TO-247-4L

Unit : mm



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4,83	5,02	5,21
A1	2,29	2,41	2,54
A2	1,91	2,00	2,16
b'	1,07	1,20	1,28
b	1,07	1,20	1,33
b1	2,39	2,57	2,94
b2	2,39	2,57	2,84
b3	1,07	1,30	1,60
b4	1,07	1,30	1,50
b5	2,39	2,53	2,69
b6	2,39	2,53	2,64
c	0,55	0,60	0,68
c1	0,55	0,60	0,65
D	23,30	23,45	23,60
D1	16,25	16,55	17,65
D2	0,95	1,19	1,25
E	15,75	15,94	16,13
E1	13,10	14,02	14,15
E2	3,68	4,40	5,10
E3	1,00	1,45	1,90
E4	12,38	13,26	13,43
e	2,54 BSC		
e1	5,08 BSC		
L	17,31	17,57	17,82
L1	3,97	4,19	4,37
L2	2,35	2,50	2,65
ØP	3,51	3,51	3,65
ØP1	7,18 REF.		
Q	5,49	5,79	6,00
S	6,04	6,17	6,30